

## IN THE CLAIMS

Claims 1-33 (Canceled).

34 (Currently Amended). A method of making a stencil for depositing material in the manufacture of semiconductor devices comprising:

forming a plurality of segmental annular openings in a stencil plate to define a central portion of the plate, and a plurality of spokes, and a remainder of said stencil plate, said spokes connecting said central portion to the remainder ~~rest~~ of said plate between adjacent segmental annular openings.

35 (Currently Amended). The method of claim 34 wherein forming a plurality of segmental annular openings in a stencil plate includes using a stencil ~~including using a plate~~ having a thickness from about 3 to about 10 mils.

36 (Previously Presented). The method of claim 34 including forming said spokes to have a length of about 1 mil.

37 (Previously Presented). The method of claim 34 including forming said central portion in a circular shape.

38 (Previously Presented). The method of claim 34 including forming at least four openings and at least four spokes.